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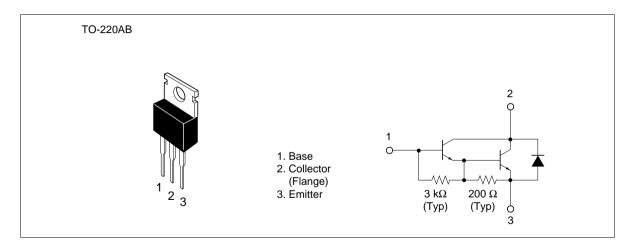
Silicon NPN Epitaxial

HITACHI

Application

Medium speed and power switching complementary pair with 2SB727(K)

Outline



Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	120	V
Collector to emitter voltage	V _{CEO}	120	V
Emitter to base voltage	V _{EBO}	7	V
Collector current	I _c	6	A
Collector peak current	I _{C(peak)}	10	A
Collector power dissipation	P_c^{*1}	40	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Value at $T_c = 25$ °C.

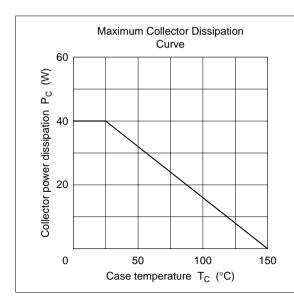


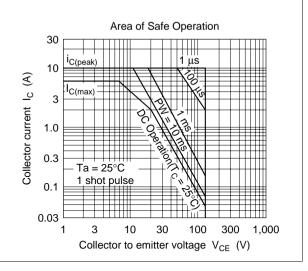
2SD768(K)

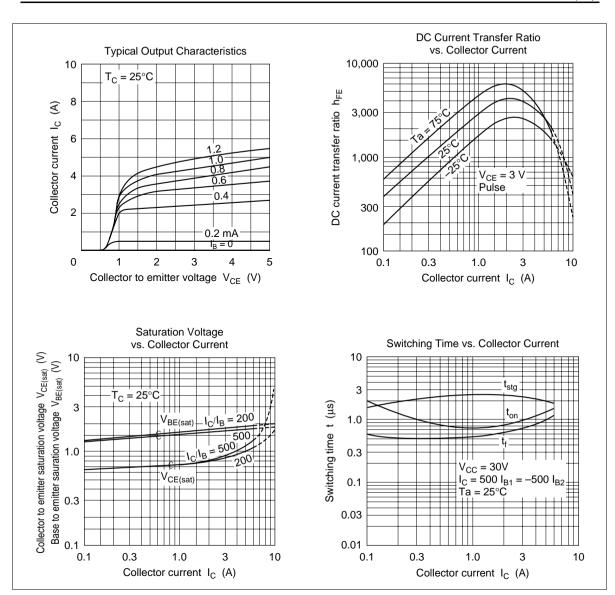
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	120	_	_	V	I_{C} = 25 mA, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{E} = 50 \text{ mA}, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	100	μΑ	V _{CB} = 120 V, I _E = 0
	I _{CEO}	_	_	10	μΑ	V _{CE} = 100 V, R _{BE} =∞
DC current transfer ratio	h _{FE}	1000	_	20000		$V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ A}^{*1}$
Collector to emitter saturation	$V_{\text{CE(sat)1}}$	_	_	1.5	V	$I_{\rm C} = 3 \text{ A}, I_{\rm B} = 6 \text{ mA}^{*1}$
voltage	V _{CE(sat)2}	_	_	3	V	$I_{\rm C} = 6A, I_{\rm B} = 60 \text{ mA}^{*1}$
Base to emitter saturation	$V_{BE(sat)1}$	_	_	2	V	$I_C = 3 \text{ A}, I_B = 6 \text{ mA}^{*1}$
voltage	$V_{\text{BE}(\text{sat})2}$	_	_	3.5	V	$I_{\rm C} = 6 \text{ A}, I_{\rm B} = 60 \text{ mA}^{*1}$
Turn on time	t _{on}	_	1.0	_	μs	$I_{\rm C} = 3 \text{ A}, I_{\rm B1} = -I_{\rm B2} = 6 \text{ mA}$
Turn off time	t _{off}	_	3.0	_	μs	$I_{\rm C} = 3 \text{ A}, I_{\rm B1} = -I_{\rm B2} = 6 \text{ mA}$

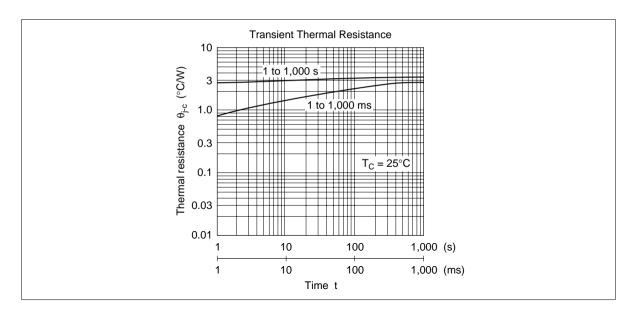
Note: 1. Pulse test.



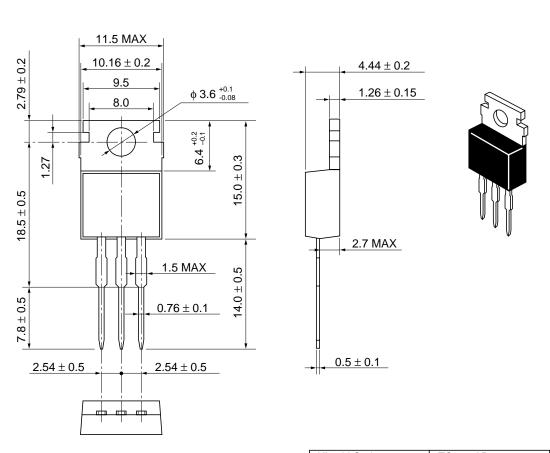




2SD768(K)



Unit: mm



Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

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